

INTRODUCTION

MLCC(Multilayer Ceramic Capacitor) is SMD(Surface Mounted Device) type capacitor that is used in wide ranges of capacitance. MLCC is paid more attentions than other capacitors due to the better frequency characteristics, higher reliability, higher withstanding voltage and so on.

MLCC is made of many layers of ceramic and inner electrodes like sandwich. Pd was used for inner electrodes. But the price of Pd was skyrocketed and Pd was replaced by the BME(Base Metal Electrode), which reduced the total cost of MLCC.

This inner electrode is connected to outer termination for surface mounting, which is composed of three layers, Cu or Ag layer, Ni plating layer, and SnPb or Sn plating layer. Most of MLCCs become Pb free by the environmental issue at present.

MLCC is divided into two classes. Class I(CoG, etc) is the temperature compensating type. It has a small TCC(Temperature Coefficient of Capacitance) and a better frequency performance. Therefore, it is used in RF applications such as cellular phone, tuner, and so on. Class II(X7R, X5R, Y5V, etc) is the high dielectric constant type, which is used in general electronic circuit. Especially high capacitance MLCC is replacing other capacitors (Tantalum and Aluminum capacitor) due to the low ESR(Equivalent Series Resistance) value.

■ FEATURE AND APPLICATION

Feature

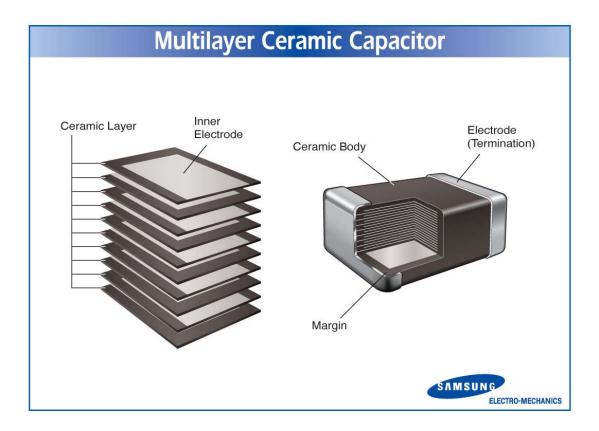
- Miniature Size
- Wide Capacitance and Voltage Range
- Highly Reliable Performance
- Tape & Reel for Surface Mount Assembly
- Low ESR
- High Q at High Frequencies
- Stable Temperature Dependence of Capacitance

Application

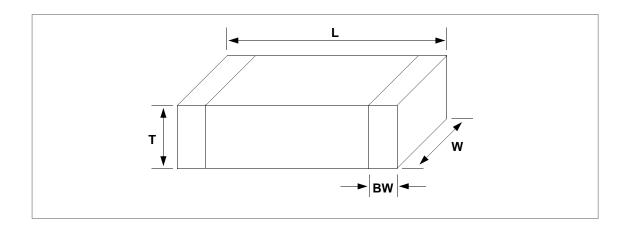
- High Frequency Circuit(Tuner, VCO, PAM etc)
- General Power Supply Circuit(SMPS etc)
- DC-DC Converter
- General Electronic Circuit



■ STRUCTURE



■ APPEARANCE AND DIMENSION



CODE	EIA CODE	DIMENSION (mm)					
CODE	LIA CODE	L	W	T (MAX)	BW		
03	0201	0.6 ± 0.03	0.3 ± 0.03	0.3 ± 0.03	0.15±0.05		
05	0402	1.0 ± 0.05	0.5 ± 0.05	0.5 ± 0.05	0.2+0.15/-0.1		
10	0603	1.6 ± 0.1	0.8 ± 0.1	0.8 ± 0.1	0.3 ± 0.2		
21	0805	2.0 ± 0.1	1.25 ± 0.1	1.25± 0.1	0.5+0.2/-0.3		
31	1206	3.2 ± 0.2	1.6 ± 0.2	1.6 ± 0.2	0.5+0.2/-0.3		
32	1210	3.2 ± 0.3	2.5 ± 0.2	2.5 ± 0.2	0.6 ± 0.3		
43	1812	4.5 ± 0.4	3.2 ± 0.3	3.2 ± 0.3	0.8 ± 0.3		
55	2220	5.7 ± 0.4	5.0 ± 0.4	3.2 ± 0.3	1.0 ± 0.3		

■ PREVIOUS PART NUMBERING

<u>CL</u> <u>10</u> <u>C</u> <u>101</u> <u>J</u> <u>B</u> <u>N</u> <u>C</u> **0 0 0 0 0 0**

- 1 SAMSUNG Multilayer Ceramic Capacitor
- 2 Type(Size)
- 3 Capacitance Temperature Characteristics
- 4 Nominal Capacitance
- 6 Capacitance Tolerance
- 6 Rated Voltage
- **7** Thickness Option
- Packaging Type

3 CAPACITANCE TEMPERATURE CHARACTERISTICS

► CLASS I (Temperature Compensation)

Symbol	EIA Code	Temperature Coefficient(PPM/℃)	* Temperature Characteristics	Operation Temperature Range
С	C0G(CH)	0 ± 30	CΔ	
Р	P2H	-150 ± 60	РΔ	
R	R2H	-220 ± 60	R∆	
S	S2H	-330 ± 60	SΔ	-55 ~ +125℃
Т	T2H	-470 ± 60	TΔ	
U	U2J	-750 ± 120	U∆	
L	S2L	+350 ~ -1000	SL	

※ Temperature Characteristics

	0.10.10.10.10.10						
Temperature Characteristics	below 2.0pF	2.2 ~ 3.9pF	above 4.0pF	above 10pF			
CΔ	C0G	C0G	C0G	C0G			
РΔ	-	P2J	P2H	P2H			
RΔ	-	R2J	R2H	R2H			
SΔ	-	S2J	S2H	S2H			
TΔ	-	T2J	T2H	T2H			
UΔ	-	U2J	U2J	U2J			

☞ K : ±250 PPM/℃

J : ±120 PPM/℃ H : ±60 PPM/℃

G : ±30 PPM/℃

► CLASS II (High Dielectric Constant)

Symbol	EIA Code	Capacitance Change (∆C : %)	Operation Temperature Range
Α	X5R	± 15	-55 ~ +85℃
В	X7R	± 15	-55 ~ +125℃
F	Y5V	+22 ~ -82	-30 ~ +85℃



4 NOMINAL CAPACITANCE

The nominal capacitance value is expressed in pico-Farad(pF) and identified by three-digit number, first two digits represent significant figures and last digit specifies the number of zeros to follow. For values below 1pF, the letter "R" is used as the decimal point and the last digit becomes significant.

example)

100 :	10 ×	10° =	10pF	
102:	10 ×	$10^2 =$	1000pF	
020 :	2 ×	10° =	2pF	
1R5:	1.5pF	=		

6 CAPACITANCE TOLERANCE

Temperature Characteristics	Symbol	Tolerance	Applicable Capacitance & Range
	В	± 0.1pF	0.5 ~ 3pF
	С	± 0.25pF	0.5 10pE
C0G(NPO)	D	± 0.5pF	0.5 ~ 10pF
or	F	± 1pF	6 ~ 10pF
T.C Series	G	± 2%	
	J	± 5%	E-24 Series for over 10pF
	K	± 10%	
. ()(==)	J	± 5%	
A(X5R)	K	± 10%	E-12 Series
B(X7R)	М	± 20%	
F(Y5V)	Z	-20% ~ +80%	E-6 Series

^{*} Please consult us for special tolerances.

6 RATED VOLTAGE

Symbol	Rated Voltage(Vdc)	Symbol	Rated Voltage(Vdc)
Q	6.3V	D	200V
Р	10V	G	500V
0	16V	I	1000V
Α	25V	J	2000V
В	50V	K	3000V
С	100V		



7 THICKNESS OPTION

Symbol	Description of the Code			
N	Standard thickness (please refer to standard thickness table on next page)			
Α	Thinner than standard thickness			
В	Thicker than standard thickness			
С	Standard Thickness High Q (Low ` D.F `)			
D	Sn-100% (High-Q)			
Е	Sn-100% (General)			

^{*} Please Consult us for other termination type.

8 PACKAGING TYPE

Symbol	Packaging	Symbol	Packaging
В	Bulk	F	Embossed Tape, 13" Reel
Р	Cassette	L	Paper 13" Reel
С	Paper Tape, 7" Reel	0	Paper 10" Reel
D	Paper Tape, 13" Reel	S	Embossed Tape, 10" Reel
E	Embossed Tape, 7" Reel		

▶ STANDARD CAPACITANCE STEP

Series		Capacitance Step										
E- 3	1.0			2.2			4.7					
E- 6	1	.0	1	.5	2	.2	3	.3	4	.7	6	.8
E-12	1.0	1.2	1.5	1.8	2.2	2.7	3.3	3.9	4.7	5.6	6.8	8.2
F 04	1.0	1.2	1.5	1.8	2.2	2.7	3.3	3.9	4.7	5.6	6.8	8.2
E-24	1.1	1.3	1.6	2.0	2.4	3.0	3.6	4.3	5.1	6.2	7.5	9.1

[※] Standard Capacitance is " Each step ×10ⁿ "



■ NEW PART NUMBERING

CL 10 C 101 J B 8 N N N C 6 6 6 6 6 6 0 0 0

- 1 SAMSUNG Multilayer Ceramic Capacitor
- 2 Size(mm)
- 3 Capacitance Temperature Characteristic
- 4 Nominal Capacitance
- **6** Capacitance Tolerance
- 6 Rated Voltage
- **7** Thickness Option
- 8 Product & Plating Method
- Samsung Control Code
- 10 Reserved For Future Use
- 1 Packaging Type

1 PRODUCT ABBREVIATION

Symbol	Product Abbreviation
CL	SAMSUNG Multilayer Ceramic Capacitor

2 SIZE(mm)

Symbol	Size(mm)					
Symbol	Length	Width				
03	0.6	0.3				
05	1.0	0.5				
10	1.6	0.8				
21	2.0	1.2				
31	3.2	1.6				
32	3.2	2.5				
43	4.5	3.2				
55	5.7	5.0				



3 CAPACITANCE TEMPERATURE CHARACTERISTIC

Symbol		Temperature Range			
С		COG	C△	0±30(ppm/℃)	
Р		P2H	P△	-150±60	
R		R2H	R△	-220±60	
S	Class I	lass S2H		-330±60	-55 ~ +125℃
Т		T2H	T△	-470±60	
U		U2J	U△	-750±60	
L		S2L	S△	+350 ~ -1000	
Α		X5R	X5R	±15%	-55 ~ +85℃
В	Class II	X7R	X7R ±15%		-55 ~ +125℃
F		Y5V	Y5V	+22 ~ -82%	-30 ~ +85℃

* Temperature Characteristic

Temperature Characteristics	Below 2.0pF	2.2 ~ 3.9pF	Above 4.0pF	Above 10pF	
СФ	C0G	C0G	C0G	C0G	
РΔ	-	P2J	P2H	P2H R2H	
RΔ	-	R2J	R2H		
SΔ	-	S2J	S2H	S2H	
ТΔ	-	T2J	T2H	T2H	
UΔ	-	U2J	U2J	U2J	

 $J: \pm 120PPM/^{\circ}C, H: \pm 60PPM/^{\circ}C, G: \pm 30PPM/^{\circ}C$

4 NOMINAL CAPACITANCE

Nominal capacitance is identified by 3 digits.

The first and second digits identify the first and second significant figures of the capacitance. The third digit identifies the multiplier. 'R' identifies a decimal point.

Example

Symbol	Nominal Capacitance
1R5	1.5pF
103	10,000pF, 10nF, 0.01 µ F
104	100,000pF, 100nF, 0.1 μ F



6 CAPACITANCE TOLERANCE

Symbol	Tolerance	Nominal Capacitance
Α	±0.05pF	
В	±0.1pF	
С	±0.25pF	Less than 10pF (Including 10pF)
D	±0.5pF	(modding Topi)
F	±1pF	
F	±1%	
G	±2%	
J	±5%	Mars than 10pF
K	±10%	More than 10pF
М	±20%	
Z	+80, -20%	

6 RATED VOLTAGE

Symbol	Rated Voltage	Symbol	Rated Voltage		
Q	6.3V	E	250V		
Р	10V	G	500V		
0	16V	Н	630V		
Α	25V	I	1,000V		
В	50V	J	2,000V		
С	100V	К	3,000V		
D	200V				

7 THICKNESS OPTION

Туре	Symbol	Thickness(T)	Spec
0603	3	0.30	±0.03
1005	5	0.50	±0.05
1608	8	0.80	±0.10
	Α	0.65	10.40
2012	С	0.85	±0.10
	F	1.25	±0.10
	С	0.85	±0.15
3216	F	1.25	±0.15
	Н	1.6	±0.20
	F	1.25	
2005	Н	1.6	±0.20
3225	I	2.0	
	J	2.5	
	F	1.25	
	Н	1.6	1000
4532	I	2.0	±0.20
	J	2.5	
	L	3.2	±0.30
	F	1.25	
	Н	1.6	+0.00
5750	I	2.0	±0.20
	J	2.5	
	L	3.2	±0.30



3 PRODUCT & PLATING METHOD

Symbol	Electrode	Termination	Plating Type			
Α	Pd	Ag	Sn_100%			
N	Ni	Cu	Sn_100% Sn_100%			
G	Cu	Cu				

9 SAMSUNG CONTROL CODE

Symbol	Description of the code	Symbol	Description of the code
Α	Array (2-element)	N	Normal
В	Array (4-element)	Р	Automotive
С	High - Q	W	3 Terminal EMI Filter
L	LICC		

10 RESERVED FOR FUTURE USE

Symbol	Description of the code
N	Reserved for future use

1 PACKAGING TYPE

Symbol	Packaging Type	Symbol	Packaging Type
В	Bulk	F	Embossing 13" (10,000EA)
Р	Bulk Case	L	Paper 13" (15,000EA)
С	Paper 7"	0	Paper 10"
D	Paper 13" (10,000EA)	S	Embossing 10"
E	Embossing 7"		



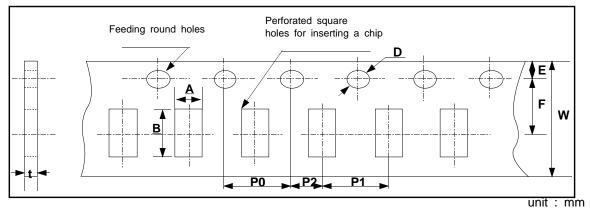
► CAPACITANCE vs CHIP THICKNESS STANDARD

De	escripti	on	0603 (0201)	1005 (0402)	1608 (0603)		12 Ty (0805			16 Ty (1206				i Туре 210)				2 Type 812)			'50 T (2220	
		L	0.6 ±0.03	1.0 ±0.05	1.6 ±0.1		2.0±0.	1	3.2±0.15 3.2 ±0.2		3.2±0.3			4.5±0.4					5.7±0.4			
	ension mm)	w	0.3 ±0.03	0.5 ±0.05	0.8 ±0.1		1.25±0.	1	1.6±	0.15	1.6 ±0.2		2.5	5±0.2			3.2	2±0.3		5.0±0.4		
		Т	0.3 ±0.03	0.5~ ±0.05	0.8 ±0.1	0.65 ±0.1	0.85 ±0.1	1.25 ±0.1	0.85 ±0.15	1.25 ±0.15	1.6 ±0.2	1.25 ±0.2			2.5 ±0.2	1.25 ±0.2	1.6 ±0.2	2.0 ±0.2	2.5 ±0.2	1.6 ±0.2	2.0 ±0.2	2.5 ±0.2
Ç	SL	50V	-	0.5~ 240	0.5 ~ 1000	0.5 ~1000	1100 ~ 1500	1600~ 2700	0.5 ~ 2700	3000~ 5600	6200~ 8200	-	-	-	-	-	-	-	-	-	-	-
CAPACITANCE RANGE (PF)	с. тс	25V	0.5~ 47	0.5~ 220	0.5 ~ 1000	-	-	3300~ 8200	1500~ 3600	3900~ 6800	7500~ 10000	-	-	-	-	-	100000	-	-	-	-	-
(PF)	C, TC (Except SL,UJ)	50V	-	0.5 ~ 180	0.5 ~ 1000	0.5 ~ 560	620~ 1000	1100~ 3300	0.5 ~ 2200	2400~ 4700	-	560~ 10000	11000 22000	24000~ 47000	-	1000~ 13000	15000~ 22000	24000~ 47000	62000~ 68000	43000	93000	130000
		6.3V	10	220	2200	ı	-	10000	1	-	10000	-	-	-	22000	1	-	-	47000	-	-	47000
		10V	10	100	1000	-	-	2200	-	-	4700~ 10000	-	-	-	22000	-	-	-	-	-	-	47000
	A (X5R)	16V	-	47	330~ 470	i	-	1000	1	-	4700	-	-	-	6800~ 10000	1	-	-	-	-	-	-
		25V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
		50V	-	6.8~ 10	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
C A P		6.3V	0.1~ 10	47~ 100	470~ 1000	-	-	1000	-	-	6800~ 10000	-	-	-	22000	-	-	-	-	-	-	-
CAPACITANCE		10V	0.1~ 10	33~ 100	220~ 470	220~ 270	330~ 470	560~ 1000	ı	1000~ 3300	4700	1500~ 2200	3300	3900~ 4700	-	ı	-	-	22000	-	-	-
	B (X7R)	16V	0.1~ 1	10~ 33	100~ 220	68~ 200	220~ 330	390~ 1000	330~ 680	1000~ 1500	2200~ 3300	1500~ 2200	3300	3900~ 4700	-	-	-	2200	-	-	-	-
R A N G E		25V	-	4.7~ 10	47~ 100	39~ 68	82~ 100	150~ 470	100~ 330	470~ 620	680~ 1000	680~ 1500	1800	2200	-	-	-	1000	-	-	-	10000
E (nF)		50V	-	0.22~ 4.7	0.22~ 100	0.22~ 39	47~ 100	220	1~ 150	220	390~ 1000	2.2~ 680	820~ 1000	-	-	10~ 1000	-	-	-	-	-	3300~ 4700
		6.3V	10~ 100	-	2200	-	-	10000	-	-	-	-	-	47000	-	-	-	-	-	-	-	-
		10V	-	220~ 330	100~ 1000	-	-	4700	-	4700	10000~ 22000	-	-	-	22000	-	-	-	-	-	-	100000
	F (Y5V)	16V	-	10~ 220	100~ 1000	10~ 680	820~ 1000	1200~ 2200	1000~ 2200	2700~ 4700	10000	3300~ 6800	10000	15000	-	-	-	22000	-	-	-	-
		25V	-	10~ 33	22~ 330	10~ 220	270~ 470	560~ 1000	470~ 1000	1200~ 2200	2700~ 3300	1000~ 3300	4700~ 10000	-	-	-	-	-	10000	-	-	-
		50V	-	2.2~ 10	2.2~ 100	2.2~ 68	82~ 150	180~ 1000	10~ 470	560~ 1000	-	100~ 1000	-	-	-	1	-	-	10000	-	-	-



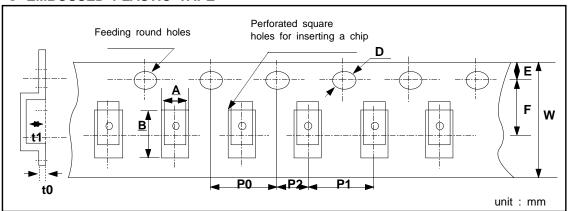
■ PACKAGING

CARDBOARD PAPER TAPE



Symbol Type		w	F	E	P1	P2	P0	D	t	A	В
	03				2.0				0.37 ±0.03	0.38 ±0.03	0.68 ±0.03
D i m	05				±0.05	2.0 ±0.05			0.6 ±0.05	0.65 +0.05/-0.1	1.15 +0.05/-0.1
e n	10	8.0 ±0.3		1.75 ±0.1	4.0 ±0.1		4.0 ±0.1	Ф1.5 +0.1/-0		1.1 ±0.2	1.9 ±0.2
s i o n	21								1.1 MAX	1.6 ±0.2	2.4 ±0.2
	31									2.0 ±0.2	3.6 ±0.2

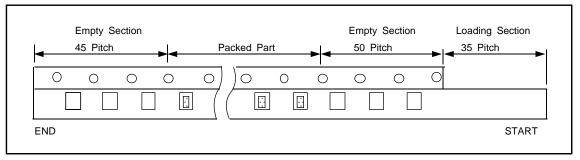
● EMBOSSED PLASTIC TAPE



	mbol /pe	W	F	E	P1	P2	P0	D	t0	t1	A	В
	21										1.45 ±0.2	2.3 ±0.2
i m e	31										2.0 ±0.2	3.6 ±0.2
n s i	32	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.1	Ф1.5 +0.1/-0	0.6 max	2.5 max	2.9 ±0.2	3.6 ±0.2
o n	43										3.6 ±0.2	4.9 ±0.2
	55										5.4 ±0.2	6.0 ±0.2



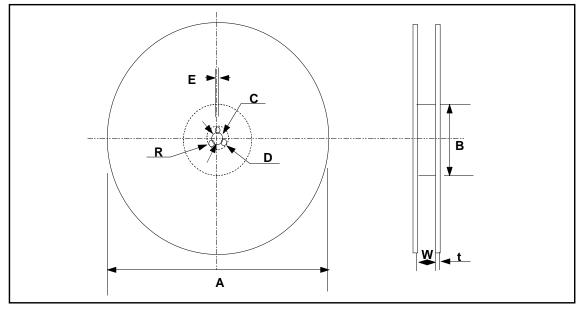
● TAPING SIZE



unit : pcs

Symbol	Cardboard Paper Tape	Embossed Plastic Tape
7" Reel	4000	2000
13" Reel	15000	-

● REEL DIMENSION



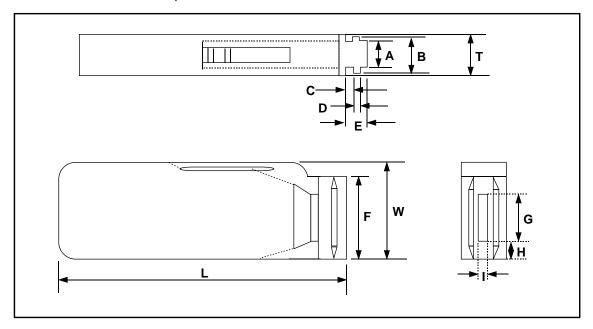
unit: mm

Symbol	Α	В	С	D	E	W	t	R
7" Reel	ф178±2.0	min.¢50						
13" Reel	ф330±2.0	min.¢70	ф13±0.5	21±0.8	2.0±0.5	10±1.5	0.8±0.2	1.0



BULK CASE PACKAGING

- Bulk case packaging can reduce the stock space and transportation costs.
- The bulk feeding system can increase the productivity.
- It can eliminate the components loss.



Symbol	Α	В	Т	С	D	E
Dimension	6.8±0.1	8.8±0.1	12±0.1	1.5+0.1/-0	2+0/-0.1	4.7±0.1

Symbol	F	W	G	Н	L	1
Dimension	31.5+0.2/-0	36+0/-0.2	19±0.35	7±0.35	110±0.7	5±0.35

QUANTITY

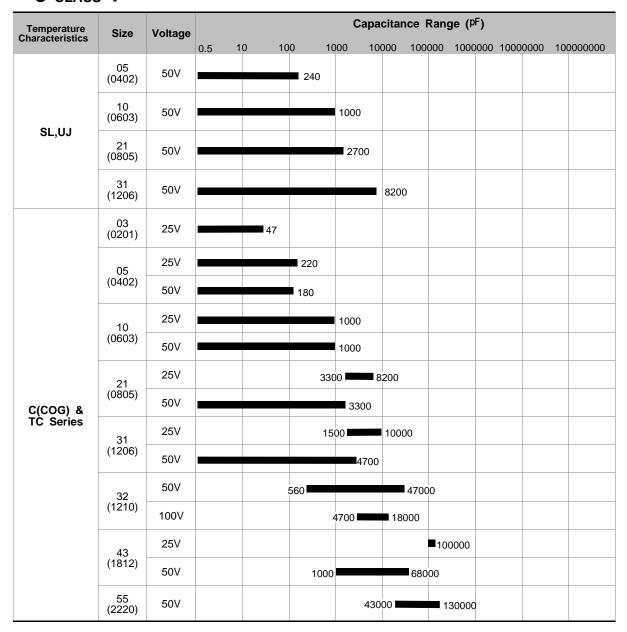
Size	05(0402)	10(0603)	21(0805)			
Size	05(0402)	10(0603)	T≤0.85mm	T≥1.0mm		
Quantity	50,000	10,000~15,000*	10,000	5,000		

^{*} Option



■ CHARACTERISTIC MAP

• CLASS I





lacktriangle CLASS II , A(X5R)

Temperature	Size	Voltage				Capacit	ance Ran	ge (pF)								
Characteristics		3	10	10	00 10	00 10	0000 100	000 100	0000 100	00000 10	0000000					
	0603	6.3V					1 0000									
	(0201)	10V					1 0000									
		6.3V						2 2000	0							
	1005	10V						= 100000)	10000000						
	(0402)	16V					470 0	00								
		50V				6800∎	10000									
		6.3V							= 22000	00						
	1608 (0603)	10V							1 00000	0						
	(****,	16V					330	000 ■ 470	000							
		6.3V								= 100000	00					
A(X5R)	2012 (0805)	10V							= 220000	00						
	(0003)	16V							1 00000	0						
		6.3V								= 100000	00					
	3216 (1206)	10V						4700	000	10000000						
		16V							47 00	0000						
		6.3V								220000	00					
	3225 (1210)	10V								220000	00					
		16V						680	0000	10000000						
	4532 (1812)	6.3V								4 700	00000					
	5750	6.3V								4700	00000					
	(2220)	10V								4 700	00000					



● CLASS II , B(X7R)

Temperature	Oi	W-14		Ca	apacita	nce Ran	ge (pF)			
Temperature Characteristics	Size	Voltage	10 10	0 1000	100	00 100	000 100	0000 100	00000 10	0000000
		6.3V	100			10000				
	03 (0201)	10V	100			10000				
		16V	100	1	000					
		6.3V			47	000	100000			
		10V			330	000	100000			
	05	16V				33000				
	(0402)	25V		470	00					
		50V	2	20	4700					
		6.3V					0000	1000000		
		10V								
	10	16V					470			
D ()(-D)	10 (0603)						220000) 		
B(X7R)		25V			47	7000				
		50V	22	20			100000			
		6.3V						1 00000	00	
		10V				22000	00	1000000		
	21 (0805)	16V				68000		1000000	 - 	00
		25V			39	000	4700	000		
		50V	22	20			220000			
		6.3V					680	00000	1000000	0
		10V					1000000	4700	0000	
	31 (1206)	16V				3300	000	33000	000	
	(1200)	25V				100000		1000000		
		50V		1000				1000000		



lacktriangle CLASS II , B(X7R)

Temperature Characteristics	Size Voltage Capacitance Range (pF)										
Characteristics	Oizc	Voltage	10	10	0 10	00 100	000 100	0000 100	0000 1000	00000 10	0000000
		6.3V								220000	00
		10V						150000	0 4700	0000	
	32 (1210)	16V						150000	o 47 00	0000	
		25V					6	80000	220000	0	
		50V			220	0			1000000	<u> </u>	
B(X7R)		10V								220000	00
	43	16V							220000	00	
	(1812)	25V							1 00000	0	
		50V				10000			1000000		
	55	25V								1 00000	00
	(2220)	50V						33000	00 🚾 470	0000	

Multilayer Ceramic Capacitor ● class II , F(Y5V)

Temperature Characteristics	Size	Voltage					Capa	citance F	Range (P	PF)		
Characteristics		Voltage	1	0	100	100	00 100	000 100	0000 100	0000 100	00000 10	0000000
	03 (0201)	6.3V					10000		100000			
		10 V						220000	33000	00		
	05	16 V					10000		220000			
	(0402)	25 V					10000	33000) 			
		50 V				2200		10000				
		6.3V								22000	00	
		10 V		100000		1000000						
	10 (0603)	16 V						100000		1000000		
	,	25 V					2200	0	330000)		
		50 V				2200			100000			
		6.3V									1 00000	000
		10 V								4 70	0000	
	21 (0805)	16 V					10000			220000		
	(0000)	25 V					10000			1000000		
F(Y5V)		50 V				2200				1000000		
		10 V							470	0000	220000	000
		16 V							1000000		1000000	
	31 (1206)	25 V						470	0000	33000		1
		50 V					10000			1000000		
		6.3V					10000			1000000		
		10 V										00000
	32	16 V									22000	
	(1210)								33000		150000	
		25 V						40000	1000000		1000000	U
		50 V						100000		1000000		
	43	16V									22000	
	(1812)	25 V									100000	000
		50 V									100000	000
	55 (2220)	10 V										1 000000



■ RELIABILITY TEST DATA

NO	ITE	М			PERFORM	ANCE			TES	T CONDITION		
1	APPEAR	RANCE	N	O ABNORN	MAL EXTERIOR	APPEARANCE		THROUGH MIC	ROSCO	DPE(×10)		
2	INSULA RESIST		SI (R	MALLER RATED VOL	500 M $\Omega\cdot\mu$ F PROD TAGE IS BELOVER 100 M $\Omega\cdot\mu$ F)	OUCT WHICHEVE	R IS		T TIME	ALL BE APPLIED IS 60 ~ 120 RA		
3	WITHSTANDING NO DIELECTRIC BREAKDOWN OR VOLTAGE MECHANICAL BREAKDOWN							CLASS II :250% C	CLASS I: 300% OF THE RATED VOLTAGE FOR 1~5 SEC, CLASS II: 250% OF THE RATED VOLTAGE FOR 1~5 SEC IS APPLIED WITH LESS THAN 50 MA CURRENT			
								CAPACITAN	CE	FREQUENCY	VOLTAGE	
		CLASS		WITHIN TOLERA	THE SPECIFIED			1,000 pF ANI BELOW	D	1灿±10%	0.5 5 1/222	
4	CAPACIT	1						MORE THA 1,000 pF	N	1kHz±10%	0.5 ~ 5 Vrms	
	ANCE							CAPACITAN	CE	FREQUENCY	VOLTAGE	
		CLASS		WITHIN	THE SPECIFIED			10μF AND BEL	_OW	1㎞±10%	1.0±0.2Vrms	
		П		TOLERA	NCE			MORE THAN 10யி		120Hz±20%	0.5±0.1Vrms	
								CAPACITAN	CE	FREQUENCY	VOLTAGE	
5	Q CLASS			OVER $30\mathrm{pF}$: Q $\geq 1,000$ LESS THAN $30\mathrm{pF}$: Q ≥ 400 +20C				1,000 pF ANI BELOW	D	12210%	0.5 ~ 5 Vrms	
		1			(C : CAPACI	TANCE)		MORE THA	N	1klb±10%	0.5 ~ 5 Vrms	
			1.	CHAR : E	3			CAPACITAN	CE	FREQUENCY	VOLTAGE	
			Ĭ	RATE) VOLTAGE	DF SPEC		10μF AND BEL	_OW	1kHz±10%	1.0±0.2Vrms	
					6.3V	0.05 max		MORE THAN	10 μF	120Hz±20%	0.5±0.1Vrms	
					10V	0.05 max						
					16V	0.035 max						
					25V	0.025 max						
				50	∨ 이상	0.025 max						
			2.	CHAR : F	=							
		CLASS			6.3V	10V		16V		25V	50V	
6	Tanδ	П		1005	-	0.125max		nax (C < 220nF) max (C≥220nF)		0.05max	0.05max	
					1608	0.16max	0.125max		0.09max		max(C≤100nF) max(C>100nF)	0.05max
				2012	0.16max	0.125max		0.09max		0.07max	0.05max	
				3216	0.16max	0.125max		0.09max		0.07max	0.05max	
			3225 0.16max 0.		0.125max		0.09max		'max(C≤6.8μF) 9max(C>6.8μF)	0.05max		
				4532	0.16max	0.16max		0.09max		-	-	
				5750		5750 0.125max				-	-	



NO	ITEM			PERFORMA	NCE	TEST CONDITION			
						THESE SYMM	METRICAL TOLERANCE APPLY TO		
			CHARACTER		MP. COEFFICIENT		ASUREMENT OF TEMPERATURE		
					(PPM/℃)	COEFFICIENT	T: ONE AT 25℃ AND AT 85℃		
			COG		0 ± 30	STEP	TEMPERATURE		
	CAPACITANCE	CLASS	PH		-150 ± 60	1	25 ± 2		
7	TEMPERATURE	I	RH		-220 ± 60	2	MIN RATED TEMP ± 2		
	COEFFICIENT		SH		-330 ± 60 -470 ± 60	1			
			UL		-750 ± 120	3	25 ± 2		
			SL		+350 ~ -1000	4	MAX RATED TEMP ± 2		
						5	25 ± 2		
8	TEMPERATURE CHARACTERISTIC S	CLASS II	CAPACITAI CHAR. A,B		GE CHANGE(%) ±15% % ~ -82%	the capacitan After capacita Max. Temp., it should be C2 - C1 C1 C1 : CAPACI TEMPI	calculated from the formula below. × 100 % TANCE AT STANDARD ERATURE(25°C) TANCE AT EACH		
9	ADHESIVE S OF TERM			N THE TER	PEELING SHALL MINAL	A 500g.f PRESSURE SHALL BE APPLIED FOR 10±1 SECOND. 500g.f SEE (FIG.1)			
		APPEARANCE	NO MECHA	ANICAL DAN	MAGE SHALL	BENDING SH	ALL BE APPLIED TO		
			OCCUR.			THE LIMIT(1n	nm) WITH 0.3mm/SEC.		
			CHAR	ACTER	CHANGE OF CAPACITANCE		EST BOARD AT THE LIMIT POINT HEN MEASURE CAPACITANCE.		
10	BENDING STRENGTH		CLA	SS I	WITHIN ±5% OR ± 0.5 pF WHICHEVER IS LARGER	CHARACTI C, A, B,			
		CAPACITANCE		A,B	WITHIN ±12.5%	50 /			
			CLASS II	F	WITHIN ±30%	45±1 SEE (FIG.2)	BENDING _ LIMIT		

NO	ITE	EM		PERF	DRMANCE			TEST CO	ONDITION	
			MORE THA		OF THE TERMINAL	S	OLDER TI	EMPERATURE	≣ : 230±5℃	
			SURFACE I	ѕ то в	E SOLDERED NEWLY,	DI	IP TIME	: 3±1 Sec		
			SO METAL	PART [DOES NOT COME	SOLDER : H63A				
			OUT OR DI	SSOLVE		FL	LUX	: RMA TYPE		
			/		<u> </u>	*P	PB-FREE			
11	SOLDER	ABILITY	 → / ,		/ //◄──			EMPERATURE		
								Sn96.5-3Ag-0.	5Cu	
			IN DRFRE	F DART	, MORE THAN 95%		ux : RM	A TYPE 3±0.1Sec		
					SURFACE IS TO BE				~120℃ FOR	10-30SEC
		SOLDERED				I IXE-IIEA	11110 . AT 00	-120 © 1 OK	10~300LO.	
		ADDEADANGE	NO M	1ECHAN	ICAL DAMAGE	DI	IP : SOLE	ER TEMPER	ATURE OF	
		APPEARANCE	SHAL	L OCCL	JR		270±	5℃		
			CHARACTE	RISTIC	CAP. CHANGE	DI	IP TIME :	10±1 SEC.		
					WITHIN ±2.5% OR				IALL BE FULL	Υ
		CAPACITANCE	CLASS	I	±0.25pF WHICHEVER			AND PREHE	ATED	
					IS LARGER		S FOLLO\	VING:		•
	RESISTANCE		CLASS II	A,B	WITHIN ±7.5%		STEP	TEMP.(℃)	TIME	
12	TO SOLDERING			F	WITHIN ±20%				(SEC.)	
	HEAT	Q	30pF AND C				1	80~100	60	
		CLASS I			: Q≥ 400+20×C	$\ \mathbb{L}$	2	150~180	60	
		Tanδ	TO SATISF		SPECIFIED			AT ROOM TE	MP. AFTER	
		CLASS II	INITIAL VAL		PRECIFIED	C	OOLING F		HOUDE	
		INSULATION RESISTANCE	TO SATISF		SPECIFIED			$SI : 24 \pm 2$ $SI : 48 \pm 4$		
		WITHSTANDING	TO SATISF		SPECIFIED		OLINO)	Hooko	
		VOLTAGE	INITIAL VALUE							
			NO MECHA	NICAL [DAMAGE SHALL	BENDING SHALL BE APPLIED TO				
		APPEARANCE	OCCUR.			TH	HE LIMIT(1mm) WITH 0).3mm/SEC.	
			CHARACTE	RISTIC	CAP. CHANGE	KEEP THE TEST BOARD AT THE LIMIT POIN				IIT POINT
					WITHIN ±2.5% OR	IN	1 5 SEC.,	THEN MEASI	URE CAPACIT	ANCE.
			CLASS	Ι	±0.25pF		CHAR.	FREQUEN	CY RANGE	
		CAPACITANCE			WHICHEVER IS LARGER		A,B,C,F	10Hz → 55	Hz → 10Hz	
			CLASS	A,B	WITHIN ±5%	1 [CHAR.	TRAVER	SED TIME	
40	VIBRATION		П	F	WITHIN ±20%		A,B,C,F	1	min	
13	TEST	Q	30pF AND C	OVER :	Q≥ 1000	TH	HE ENTIR	E FREQUENC	CY RANGE	1
		CLASS I	LESS THAN	1 30 pF :	$Q{\geq}\ 400\text{+}20{\times}C$			TO 55Hz ANI	- ,	
		Tan $δ$	TO SATISF	Y THE	SPECIFIED	Т	O 10Hz, S	SHALL BE TR	AVERSED	
		CLASS II	INITIAL VA	LUE		IN	I 1 MINUT	ΓE.		
		INSULATION	TO SATISF	Y THE	SPECIFIED				PERFORMED	
		RESISTANCE	INITIAL VA						RE MUTUALL	Y
								CULAR DIREC		
							-UK 101/	AL PERIOD O	r 6 HOURS.	

^{*} THE INITIAL VALUE OF HIGH DIELECTRIC CONSTANT SERIES SHALL BE MEASURED

AFTER THE HEAT TREATMENT OF 150 +0/-10°C, 1Hr AND SITTING OF 48±4hr AT ROOM TEMPERATURE & ROOM HUMIDITY.



NO		ГЕМ			DEDEC	RMANCE	TEST CONDITION						
NO	11		NO MES	IANIOA			000115						
		APPEARANCE				GE SHALL			-	TEMPERATURE : 40 ± 2 °C RELATIVE HUMIDITY:90~95 %RH			
			CHARAC	TERIST	IC CA	PACITANO	E CHAN	IGE					
				WIT	HIN ±5%	OR		TEST TIME	: 500 +12/-0 Hr.				
		CAPACITANCE	CLA	±0.	$\pm 0.5 \mathrm{pF}$ WHICHEVER			MEAGURE AT ROOM TEMPERATURE					
		0/11/10/1/11/02		IS I	ARGER			MEASURE AT ROOM TEMPERATURE AFTER COOLING FOR					
			CLASS	WIT	HIN ±12.5	%		CLASS I : 2					
			П	F	WIT	HIN ±30%)		CLASS I : 4				
		0	30pF AND	OVER	: Q≥ 3	350			OLAGOI	10±4 III.			
	HUMIDITY	Q CLASS I	10 ~30pF	: 0)≥ 275 +	2.5×C			6.3V	0.405.14437.40			
14	(STEADY	CLASS 1	LESS TH	AN 10pl	F : Q≥ 2	200 + 10×	С		Tanδ	0.125 MAX *Condition			
	STATE)			25V						1005 C ≥0.22 <i>μ</i> F			
	,		CHAR.	AND OVER	16V	10V	6.3V	4V		1608 C ≥2.2 <i>μ</i> F			
		Tanδ	A,B	0.05	0.05 M	0.05	0.075	0.1	CLASSII	2012 C ≥4.7 <i>μ</i> F			
		CLASS II	А,Б	0.05	0.05 101/	MAX	MAX	MAX	(A,B)	3216 C ≥10.0 <i>μ</i> F			
		OLAGO II		0.075	0.1MA (C < 1.0)	νF)	0.195	0.25	(-,-)	3225 C ≥22.0μF			
			F	MAX	0.125 MAX	MAX	MAX	MAX		4532 C ≥47.0 <i>μ</i> F			
					(C≥1.0)	ιF)				5750 C ≥100.0μF			
		INSULATION	MINIMUM	INSUL	ation R	ESISTANC	E:						
		RESISTANCE	1,000 MΩ	OR 50M	Ω·μF PRO	DDUCT WI	R IS						
		REGIOTANCE	SMALLER										
		APPEARANCE	NO MECH	HANICA	L DAMA	GE SHALL	OCCUR		APPLIED VOL	TAGE :			
	,								RATED VOLTAGE TEMPERATURE : 40 ± 2 $^{\circ}\mathrm{C}$				
			CHARAC	TERIST	IC CAF	PACITANCI	E CHANG	GE					
					WIT	HIN ±7.5%	6 OR		RELATIVE HUMIDITY:90~95%RH TEST TIME: 500 +12/-0 Hr.				
			CLA	SS I	±0.	75pF WHIC	HEVER		CURRENT APPLIED : 50mA MAX.				
				IS I	ARGER			<initial measurement=""></initial>					
				A,B WITHIN ±12.5%			CLASS II SHOULD BE MEASURED						
					WIT	HIN ±30%			INITIAL VALUE AFTER BE HEAT-TREATED FOR 1 HR IN 150°C+0/-10°C AND BE LEFT FOR 48±4HR AT ROOM TEMPERATURE. <latter measurement=""> CLASS I SHOULD BE MEASURED AFTER</latter>				
	-	CAPACITANCE											
						THIN +30~։ 5 C>0.47և							
			CLASS			8 C>1.0µF							
			П	F		8 C>1.0μ1 2 C>4.7μF				±2 HRS IN ROOM			
	MOISTURE					6 C>10.0µ	=		TEMPERATUR	RE AND HUMIDITY.			
15	RESISTANCE				322	5 C>22.0µ	F		CLASS II SH	OULD BE MEASURED			
						2 C>47.0µ			LATTER VALU				
		Q	30pF AND	OVER	: Q≥ 2	200				ED FOR 1 HR IN 150°C+0/-10			
		CLASS I	30pF AND	BELO\	W : Q≥	100 + 10	3×C		TEMPERATUR	EFT FOR 48±4HR AT ROOM			
				25V									
			CHAR.	AND OVER	16V	10V	6.3V	4V	6.3V Tanδ	0.125 MAX *Condition			
		- c		0.05	0.05	0.05	0.075	0.4		1005 C ≥0.22μF			
		Tanδ CLASS II	A,B	0.05 MAX	MAX	0.05 0.05 MAX MAX		0.1 MAX		1608 C ≥2.2μF 2012 C ≥4.7μF			
					0.1MA	x			CLASS II	3216 C ≥10.0μF			
			F	0.075 MAX	(C <1.0) 0.125M	dF) 0.15	0.195 MAX	0.25 MAX	(A,B)	3225 C ≥22.0μF			
			<u> </u>		(C≥1.0µ	(F)				4532 C ≥47.0μF			
		INCLUATION	MINIMUM	INSUL	ATION R	ESISTANC	E:			5750 C ≥100.0µF			
		INSULATION RESISTANCE	500 MΩ O	R 25MΩ·	μF PROD	OUCT,							
		RESISTANCE	WHICHE	/ER IS	SMALLEI	₹.							
						· ·							



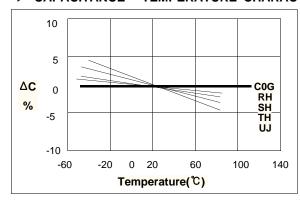
NO	ITE	EM			PERFORM	IANCE			TEST CONDITION																
		APPEARANCE	NO MECI	HANICA	L DAMAGI	E SHAL	L OCCI	JR	APPLIED VOLTAGE: 150%, 200% OF RATED VOLTAGE TEST TIME: 1000 +48/-0 Hr. CURRENT APPLIED: 50mA MAX.																
									CHAR.			TEMP.													
			CHARAC	TERIST	IC	CAP.	CHANG	E		CLAS		125 ±3 ℃													
			CLAS	SS I		WITHIN ±3% OR ±0.3pF, WHICHEVER IS LARGER				SS [В	85 ±3 ℃ 125 ±3 ℃													
				A,B		N ±12.		OLIK		ı	F	85 ±3 ℃													
				Α,υ					<initial< td=""><td>MEA</td><td>SUREMENT></td><td><u> </u></td></initial<>	MEA	SUREMENT>	<u> </u>													
		045401741105				N ±30%						EASURED INITIAL													
		CAPACITANCE				N+30~4 C>0.47						REATED FOR 1													
			CLASS			C>0.47 C>1.0µF					M TEMPERA	BE LEFT FOR 48± TURE.													
			П	F		C>1.0ր։ C>4.7µF					ASUREMENT:														
						C>4.7 րг C>10.0բ			CLASS I	SHC	OULD BE ME	ASURED AFTER													
40	HIGH					C>22.01				LEFT FOR 24±2 HRS IN ROOM															
16	TEMPERATURE					C>47.0 ₁					RE AND HUM IOULD BE ME														
	RESISTANCE		20pE AND	OVED	: Q ≥ 3				CLASS II SHOULD BE MEASURED LATTER VALUE AFTER BE HEAT-TREATED FOR 1																
		Q	-				HR IN 150℃+0/-10℃ AND BE LEFT FOR 48±																		
		CLASS I	10 ~ 30 pF : Q ≥ 275 + 2.5×C LESS THAN 10pF :Q ≥200 + 10×C							ROO	M TEMPERA	TURE.													
				25V								ation Conditions													
			CHAR.	AND OVER	16V	10V	6.3V	4V				C>0.47μF C ≥2.2μF													
		_		0.05	0.05	0.05	0.075	0.1				C ≥4.7μF													
		Tan∂ CLASS II	A,B	MAX	MAX	MAX	MAX	MAX	CLASS		3216	C ≥10.0 <i>µ</i> F													
			CLASSII	CLASSII	CLASS ∏	CLASSⅡ	CLASSII	CLASSII	CLASSII	CLASSII	CLASSII	CLASSⅡ	CLASS II	CLASSII	CLASS II			0.4MAV				(A,B,	F)	3225	C ≥22.0µF
			F	0.075	0.1MAX (C<1.0µF) 0.125MAX	0.15	0.195	0.25				C ≥47.0μF													
				MAX	(C≥1.0μF)	MAX	MAX	MAX			5750 C ≥100.0µF														
		INSULATION		MINIMUM INSULATION RESISTANCE: 1,000 № OR 50№ μ/г PRODUCT						(TWICE OF RATED VOLTAGE WILL BE APPLIED TO ALL SERIES BUT ABOVE)															
		RESISTANCE	WHICHEVER IS SMALLER						** HOWEVER, A/B																
		APPEARANCE	NO MECI	HANICA	L DAMAGI	SHAL	L OCCI	JR	CAPAC	TOR	S SHALL BE	SUBJECTED													
			CHARAC	TERIST		CAP. N ±2.5	CHANG	E			CLES OF TI	HE AS FOLLOWING													
			CLAS	SS I				EVER IS	STEP		TEMP.(℃)	TIME(MIN)													
		CAPACITANCE			LARG	ER			. 1		MIN.RATED ΓΕΜΡ.+0/-3	30													
	TEMPERATURE		CLASS II	A,B		N ±7.5			2		25	2~3													
17	CYCLE					N ±20%	6			N	MAX.RATED														
		Q CLASS I	-		R : Q ≥ F:Q ≥400				3		ΓΕΜΡ.+3/-0	30													
		Tan δ	TO SATIS	SFY TH	E SPECIFI	ED			4		25	2~3													
		CLASS II	INITIAL V	'ALUE					MEASU	RE A	T ROOM TE	EMPERATURE													
		INSULATION	N TO SATISFY THE SPECIFIED						AFTER	coo	LING FOR														
		RESISTANCE	INITIAL VALUE						CLASS I : 24±2 Hr.																
		REGIOTANOL		, \LUL					CLASS	Ⅱ : 4	8±4 Hr.														

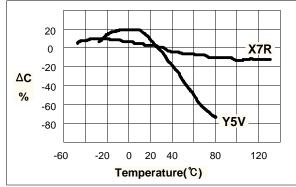


CHARACTERISTIC GRAPH

• ELECTRICAL CHARACTERISTICS

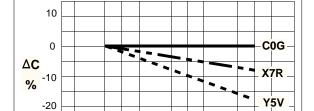
▶ CAPACITANCE - TEMPERATURE CHARACTERISTICS





► CAPACITANCE - DC VOLTAGE CHARACTERISTICS ► CAPACITANCE CHANGE - AGING

20 COG 50V 0 X7R ΔC 50V % -60 Y5V -80 -10020 25 30 35 10 15 40 DC Voltage(Vdc)



1000

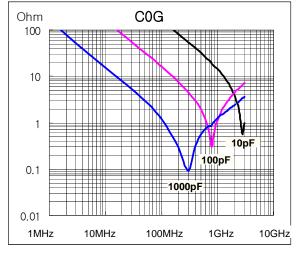
Time(Hr)

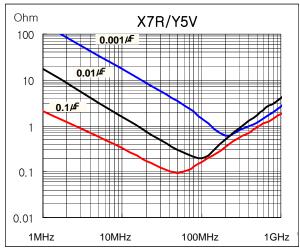
10000

50 100

-30

▶ IMPEDANCE - FREQUENCY CHARACTERISTICS







APPLICATION MANUAL

Storage Condition

► Storage Environment

The electrical characteristics of MLCCs were degraded by the environment of high temperature or humidity. Therefore, the MLCCs shall be stored in the ambient temperature and the relative humidity of less than 40°C and 70%, respectively. Guaranteed storage period is within 6 months from the outgoing date of delivery.

Corrosive Gases

Since the solderability of the end termination in MLCC was degraded by a chemical atmosphere such as chlorine, acid or sulfide gases, MLCCs must be avoid from these gases.

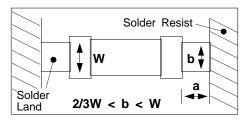
▶ Temperature Fluctuations

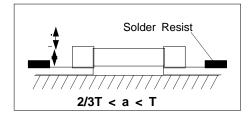
Since dew condensation may occur by the differences in temperature when the MLCCs are taken out of storage, it is important to maintain the temperature-controlled environment.

Design of Land Pattern

When designing printed circuit boards, the shape and size of the lands must allow for the proper amount of solder on the capacitor. The amount of solder at the end terminations has a direct effect on the crack. The crack in MLCC will be easily occurred by the tensile stress which was due to too much amount of solder. In contrast, if too little solder is applied, the termination strength will be insufficiently. Use the following illustrations as guidelines for proper land design.

Recommendation of Land Shape and Size





Adhesives

When flow soldering the MLCCs, apply the adhesive in accordance with the following conditions.

► Requirements for Adhesives

They must have enough adhesion, so that, the chips will not fall off or move during the handling of the circuit board.

They must maintain their adhesive strength when exposed to soldering temperature.

They should not spread or run when applied to the circuit board.

They should harden quickly.

They should not corrode the circuit board or chip material.



They should be a good insulator.

They should be non-toxic, and not produce harmful gases, nor be harmful when touched.

Application Method

It is important to use the proper amount of adhesive. Too little and much adhesive will cause poor adhesion and overflow into the land, respectively.

► Adhesive hardening Characteristics

To prevent oxidation of the terminations, the adhesive must harden at 160° C or less, within 2 minutes or less.

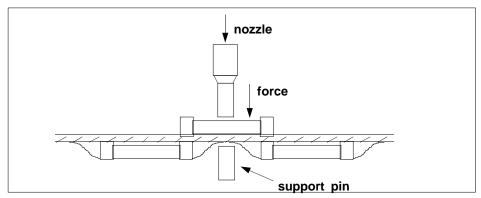
Mounting

► Mounting Head Pressure

Excessive pressure will cause crack to MLCCs. The pressure of nozzle will be 300g maximum during mounting.

▶ Bending Stress

When double-sided circuit boards are used, MLCCs first are mounted and soldered onto one side of the board. When the MLCCs are mounted onto the other side, it is important to support the board as shown in the illustration. If the circuit board is not supported, the crack occur to the ready-installed MLCCs by the bending stress.



Flux

Although the solderability increased by the highly-activated flux, increase of activity in flux may also degrade the insulation of the chip capacitors. To avoid such degradation, it is recommended that a mildly activated rosin flux(less than 0.2% chlorine) be used.



Soldering

Since a multilayer ceramic chip capacitor comes into direct contact with melted solder during soldering, it is exposed to potentially mechanical stress caused by the sudden temperature change. The capacitor may also be subject to silver migration, and to contamination by the flux. Because of these factors, soldering technique is critical.

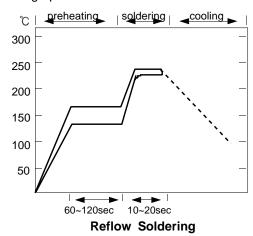
Soldering Methods

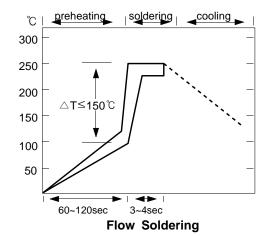
Method	Classification					
Reflow	- Overall heating	Infrared raysHot plateVPS(vapor phase)				
soldering	- Local heating	Air heaterLaserLight beam				
Flow soldering	- Single wave - Double wave	-				

^{*} We recommend the reflow soldering method.

▶ Soldering Profile

To avoid crack problem by sudden temperature change, follow the temperature profile in the adjacent graph.



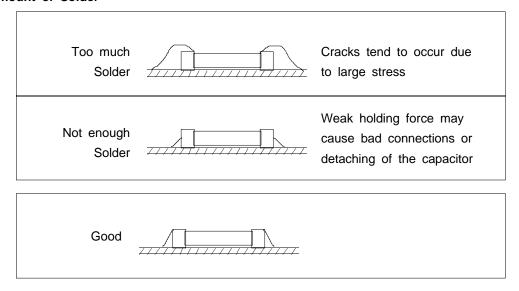


Manual Soldering

Manual soldering can pose a great risk of creating thermal cracks in chip capacitors. The hot soldering iron tip comes into direct contact with the end terminations, and operator's carelessness may cause the tip of the soldering iron to come into direct contact with the ceramic body of the capacitor. Therefore the soldering iron must be handled carefully, and close attention must be paid to the selection of the soldering iron tip and to temperature control of the tip.



► Amount of Solder



Cooling

Natural cooling using air is recommended. If the chips are dipped into solvent for cleaning, the temperature difference($\triangle T$) must be less than 100 $^{\circ}C$

6-6. Cleaning

If rosin flux is used, cleaning usually is unnecessary. When strongly activated flux is used, chlorine in the flux may dissolve into some types of cleaning fluids, thereby affecting the chip capacitors. This means that the cleaning fluid must be carefully selected, and should always be new.

▶ Notes for Separating Multiple, Shared PC Boards.

A multi-PC board is separated into many individual circuit boards after soldering has been completed. If the board is bent or distorted at the time of separation, cracks may occur in the chip capacitors. Carefully choose a separation method that minimizes the bending of the circuit board.

■ CROSS REFERENCE

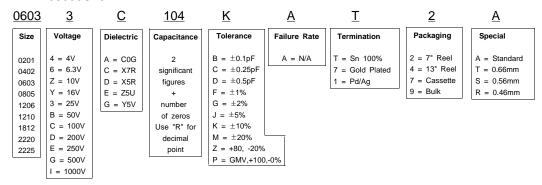
P/N	COMPANY	SAMSUNG	AVX	JOHANSON	KEMET	KYOCERA	MURATA	NOVACAP	PANASONIC	ROHM	TAIYO - YUDEN	TDK	VITRAMON
① COMPANY	MODEL(MLCC)	CL	-	-	С	СМ	GRM	-	ECJ	MCH	MK	С	۸٦
	0201(0603)	03	-	-	-	03	33	-	Z	-	063	0603	-
	0402(1005)	05	0402	R07	0402	05	36	0402	0	15	105	1005	0402
	0603(1608)	10	0603	R14	0603	105	39	0603	1	18	107	1608	0603
	0805(2012)	21	0805	R15	0805	21	40	0805	2	21	212	2012	0805
② SIZE (EIA/JIS)	1206(3216)	31	1206	R18	1206	316	42-6	1206	3	31	316	3216	1206
	1210(3225)	32	1210	S41	1210	32	42-2	1210	4	32	325	3225	1210
	1808(4520)	42	1808	R29	1808	42	-	1808	-	-	-	4520	1808
	1812(4532)	43	1812	S43	1812	43	43-2	1812	-	43	432	4532	1812
	2220(5750)	55	-	-	2220	55	44-1	2221	-	-	550	5650	-
	COG(NPO)	С	Α	N	G	CG	COG/CH	N	С	А	С	COG/CH	A
	P2H(N150)	Р	s	-	-	Р	P2H	-	P	-	Р	PH	-
	R2H(N220)	R	1	-	-	R	R2H	-	R	-	R	RH	-
	S2H(N330)	s	3	-	-	s	S2H	-	s	-	S	SH	-
③ TEMPERATURE	T2H(N470)	Т	0	-	-	Т	T2H	-	Т	-	Т	TH	-
CHARACTERISTIC	U2J(N750)	U	Z	-	-	U	U2J	-	U	UJ	U	UJ	-
	S2L	L	Y	-	-	SL	SL	-	G	SL	SL	SL	-
	X7R	В	С	w	R(X)	X7R	X7R	В	В	С	BJ	X7R(B)	Y(X)
	Z5U	E	Е	z	U	-	Z5U	Z	-	E	-	Z5U	U
	Y5V	F	G	Y	v	Y5V	Y5V	Y	F	F	F	Y5V	-
Nominal	CAPACITANCE			E>	() 103=10,0	00pF 221=	=220pF 225	5=2,200,000pF=	2.2/ ^F 1R5=1.	5pF 010=1	pF		
© CAPACITAN	CE TOLERANCE			B:±0.1pF C:	±0.25pF	D:±0.5pF F	:±1% G:±	±2% J:±5%	6 K:±10%	M:±20%	Z:-20~+80%	6	
	6.3V	Q	6	-	9	06	6.3	-	OJ	-	J	0J	-
	10 V	Р	z	100	8	10	10	-	1A	4	L	1A	-
	16 V	0	Y	160	4	16	16	160	1C	3	E	1C	J
	25 V	А	3	250	3	25	25	250	1E	2	Т	1E	Х
	50 V	В	5	500	5	50	50	500	1H	5	U	1H	Α
	100 V	С	1	101	1	100	100	101	2A	1	-	2A	В
® RATED	200V	D	2	201	2	200	200	201	2D	-	-	-	С
VOLTAGE	250V	E	V	-	-	250	250	251	-	-	-	2E	-
	500V	G	7	501	-	500	500	501	-	-	-	-	E
	630V	Н	-	-	-	630	630	-	-	-	-	2J	-
	1000V	I	Α	102	-	1000	1K	102	-	-	-	3A	G
	2000V	J	G	202	-	2000	2K	202	-	-	-	3D	-
	3000V	К	Н	302	-	3000	3K	302	-	-	-	3F	Н
	4000V	-	J		-	4000	-	402	-	-	-	-	-
7 TERMINATION	NICKEL BARRIER	N	Т	V	С	Α	(GRM)	N	-	(MCH)	-	-	х
	Ag/Pd	Р	1	-	-	В	(GR)	Р	-	(MC)	-	-	F
	BULK(VINYL)	В	9	(NONE)	-	В	РВ	*	х	-	В	В	В
® PACKAGE	PAPER TAPING	С	2, 4	T, R	-	T, L	PT	Т	E,V,W	K, L	Т	Т	C, P
W PACKAGE	PLASTIC TAPING	E	1, 3	E, U	-	H, N	PT	-	F, Y	P, Q	Т	-	T, R



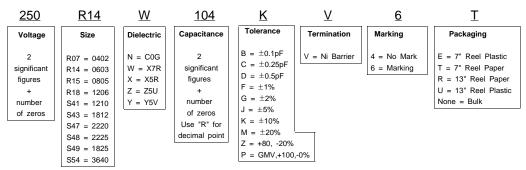
► SAMSUNG : CL10B104KA8NNNC

CL	<u>10</u>	<u>B</u>	<u>104</u>	<u>K</u>	<u>A</u>	<u>8</u>	<u>N</u>	<u>N</u>	<u>N</u>	<u>C</u>
Series	Size	Dielectric	Capacitance	Tolerance	Voltage	Thickness	Electrode/	Products	Special	Packaging
							Termination/			
	03 = 0201	C = C0G	2	$A = \pm 0.05pF$	Q = 6.3V	3 = 0.30	Plating	A = Array	Various	B = Bulk
	05 = 0402	P = P2H	significant	$B = \pm 0.1pF$	P = 10V	5 = 0.50		(2-element)		P = Cassette
	10 = 0603	R = R2H	figures	$C = \pm 0.25pF$	O = 16V	8 = 0.80	A = Pd/Ag/	B = Array		C = Paper 7"
	21 = 0805	S = S2H	+	$D = \pm 0.5pF$	A = 25V	A = 0.65	Sn 100%	(4-element)		D = Paper 13"
	31 = 1206	T = T2H	number	F = ±1%	B = 50V	C = 0.85	N = Ni/Cu/	C = High - Q		(10,000EA)
	32 = 1210	U = U2H	of zeros	$G = \pm 2\%$	C = 100V	H = 1.60	Sn 100%	L = LICC		E = Embossing 7"
	43 = 1812	L = S2L	Use "R" for	$J = \pm 5\%$	D = 200V	I = 2.00	G = Cu/Cu/	N = Normal		F = Embossing 13"
	55 = 2220	B = X7R	decimal point	$K = \pm 10\%$	E = 250V	J = 2.50	Sn 100%	P = Automotive		L = Paper 13"
		A = X5R		$M = \pm 20\%$	G = 500V	L = 3.20		W = 3 terminal		(15,000EA)
		F = Y5V		Z = +80,-20%	H = 630V		ı.	chip		O = Paper 10"
				,	I = 1000V			•	_	S = Embossing 10"

► AVX: 06033C104KAT2A



► JOHANSON: 250R14W104KV6T



► KEMET: C0603C104K3RAC

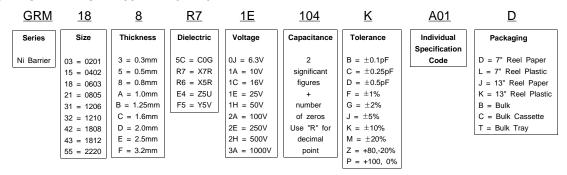
<u>C</u>	0603	<u>C</u>	<u>104</u>	<u>K</u>	<u>3</u>	<u>R</u>	<u>A</u>	<u>C</u>					
Series	Size	Specification	Capacitance	Tolerance	Voltage	Dielectric	Failure Rate	Termination					
	0402 0603 0805 1206 1210 1812 2220 2225	C = Standard A = GR900 P = Mil-C-55681 CDR01-CDR06 N = Mil-C-55681 CDR31-CDR35 Z = Mil-C-123 E = Mil Equivalent (Group A Only)	2 significant figures + number of zeros Use "R" for decimal point	$B = \pm 0.1 pF$ $C = \pm 0.25 pF$ $D = \pm 0.5 pF$ $F = \pm 1\%$ $G = \pm 2\%$ $J = \pm 5\%$ $K = \pm 10\%$ $M = \pm 20\%$ $Z = +80, -20\%$	9 = 6.3V 8 = 10V 4 = 16V 3 = 25V 5 = 50V 1 = 100V 2 = 200V	G = C0G R = X7R P = X5R U = Z5U X = BX(Mil) V = Y5V	A = Standard M = 1.0 (Mil) P = 0.1 (Mil) R = 0.01 (Mil) S = 0.001 (Mil)	C = Ni w/Tin Plate H = Ni w/Solder T = Silver G = Gold Plated					
				P = +100, 0%									



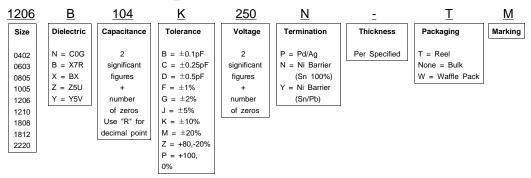
► KYOCERA: CM105X7R104K25AT

<u>CM</u>	<u>105</u>	<u>X7R</u>	<u>104</u>	<u>K</u>	<u>25</u>	<u>A</u>	I
Series	Size	Dielectric	Capacitance	Tolerance	Voltage	Termination	Packaging
	03 = 0201 05 = 0402 105 = 0603 21 = 0805 316 = 1206 32 = 1210 42 = 1808 43 = 1812 55 = 2220	CG X8R X7R X5R Z5U Y5V	2 significant figures + number of zeros Use "R" for decimal point	$B = \pm 0.1 pF$ $C = \pm 0.25 pF$ $D = \pm 0.5 pF$ $F = \pm 1\%$ $G = \pm 2\%$ $J = \pm 5\%$ $K = \pm 10\%$ $M = \pm 20\%$ $Z = +80, -20\%$ $P = +100, 0\%$	04 = 4V 06 = 6.3V 10 = 10V 16 = 16V 25 = 25V 50 = 50V 100 = 100V 250 = 250V 500 = 500V 1000 = 1000V	A = Ni Barrier	T = 7" Reel (4mm Pitch) L = 13" Reel (4mm Pitch) H = 7" Reel (2mm Pitch) N = 13" Reel (2mm Pitch) B = Bulk (Vinyl Bags) C = Bulk Cassette

► MURATA : GRM188R71E104KA01D



► NOVACAP: 0603B104K250N_TM

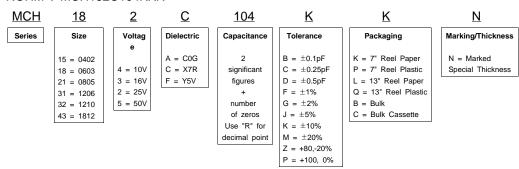


▶ PANASONIC : ECJ1EB1E104K

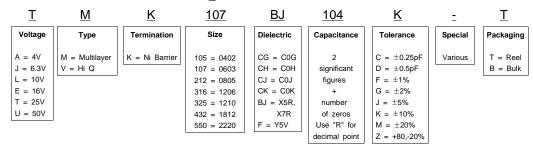
<u>ECJ</u>	1	<u>E</u>	<u>B</u>	<u>1E</u>	<u>104</u>	<u>K</u>
Series	Size	Packaging	Dielectric	Voltage	Capacitance	Tolerance
	Z = 0201 0 = 0402 1 = 0603 2 = 0805 3 = 1206 4 = 1210	X = Bulk E = Paper 2mm V = Paper 4mm F, Y = Plastic 4mm W = Large Reels 2mm Z = Large Reels 4mm C = Bulk Cassette	C = C0G B = X7R, X5R F = Y5V	0J = 6.3V 1A = 10V 1C = 16V 1E = 25V 1H = 50V 2A = 100V 2D = 200V	2 significant figures + number of zeros Use "R" for decimal point	C = $\pm 0.25pF$ D = $\pm 0.5pF$ F = $\pm 1\%$ J = $\pm 5\%$ K = $\pm 10\%$ M = $\pm 20\%$ Z = $+80$, -20%



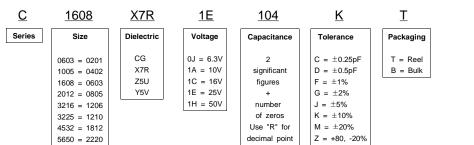
► ROHM: MCH182C104KKN



► TAIYO-YUDEN: TMK107BJ104K_T



▶ TDK : C1608X7R1E104KT



► VITRAMON: VJ0603Y104KXXMC

